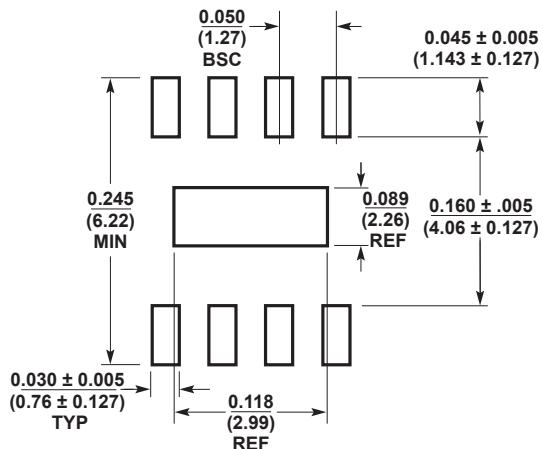
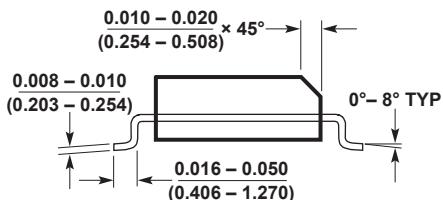


S8E Package
8-Lead Plastic SOIC (Narrow 0.150 Inch) Exposed Pad
 (Reference LTC DWG # 05-08-1857)



RECOMMENDED SOLDER PAD LAYOUT



NOTE:

1. DIMENSIONS IN INCHES
 (MILLIMETERS)

2. DRAWING NOT TO SCALE

3. THESE DIMENSIONS DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS.
 MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.010" (0.254 mm)

